

April 2016

QRE1113, QRE1113GR Miniature Reflective Object Sensor

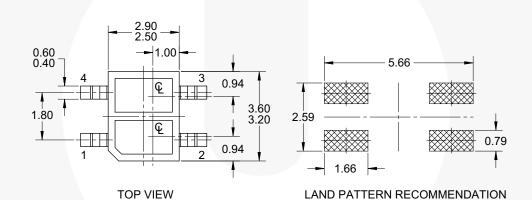
Features

- Phototransistor Output
- No Contact Surface Sensing
- Miniature Package
- Lead Form Style: Gull Wing

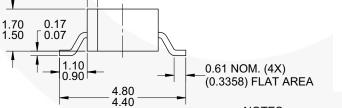
- Two Leadform Options: Through Hole (QRE1113)
 - SMT Gull Wing (QRE1113GR)
- Two Packaging Options: Tube (QRE1113)

Tape and Reel (QRE1113GR)

QRE1113GR Package Dimensions







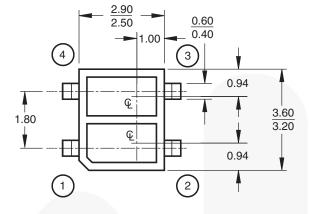
SIDE VIEW

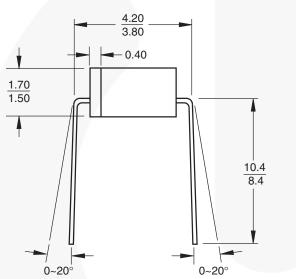
NOTES:

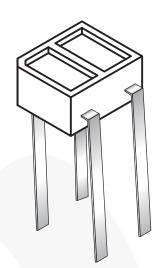
- A. NO INDUSTRY STANDARD APPLIES
 TO THIS PACKAGE
 B. ALL DIMENSIONS ARE IN MILLIMETERS
 C. TOLERANCE OF ±0.15MM ON ALL
 NON-NOMINAL DIMENSIONS
 D. DRAWING ELL ENAME: MCT APPLIATATION

- D. DRAWING FILENAME: MKT-ARU313Arev2

QRE1113 Package Dimensions(1, 2)



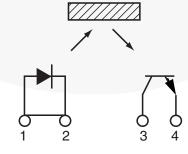




Notes:

- 1. Dimensions for all drawings are in millimeters.
- 2. Tolerance of ±0.15 mm on all non-nominal dimensions.

Schematic



Pin 1: Anode Pin 2: Cathode Pin 3: Collector Pin 4: Emitter

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

Symbol	Parameter	Value	Unit
T _{OPR}	Operating Temperature	-40 to +85	
T _{STG}	Storage Temperature	-40 to +90	°C
T _{SOL-I}	Soldering Temperature (Iron) ^(4 5, 6)	240 for 5 sec	°C
T _{SOL-F}	Soldering Temperature (Flow) ^(5, 6)	260 for 10 sec	°C
EMITTER			
I _F	Continuous Forward Current	50	mA
V _R	Reverse Voltage	5	V
I _{FP}	Peak Forward Current ⁽⁷⁾	1	А
P _D	Power Dissipation ⁽³⁾ 75		mW
SENSOR			
V _{CEO}	Collector-Emitter Voltage	30	V
V _{ECO}	Emitter-Collector Voltage	5	V
I _C	Collector Current	20	mA
P _D	Power Dissipation ⁽³⁾	50	mW

Electrical / Optical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
INPUT DIO	DE				•	
V _F	Forward Voltage	I _F = 20 mA		1.2	1.6	V
I _R	Reverse Leakage Current	V _R = 5 V			10	μΑ
λ_{PE}	Peak Emission Wavelength	I _F = 20 mA		940		nm
OUTPUT TI	RANSISTOR					
I _D	Collector-Emitter Dark Current	$I_F = 0 \text{ mA}, V_{CE} = 20 \text{ V}$			100	nA
COUPLED						
I _{C(ON)}	On-State Collector Current	$I_F = 20 \text{ mA}, V_{CE} = 5 \text{ V}^{(8)}$	0.10	0.40		mA
I _{CX}	Cross-Talk Collector Current	$I_F = 20 \text{ mA}, V_{CE} = 5 \text{ V}^{(9)}$			1	μΑ
V _{CE(SAT)}	Saturation Voltage				0.3	V
t _r	Rise Time	$V_{CC} = 5 \text{ V}, I_{C(ON)} = 100 \mu\text{A},$		20		μS
t _f	Fall Time	$R_L = 100 \text{ k}\Omega$		20		μS

Notes:

- 3. Derate power dissipation linearly 1.00 mW/°C above 25°C.
- 4. RMA flux is recommended.
- 5. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 6. Soldering iron 1/16" (1.6mm) from housing.
- 7. Pulse conditions: $tp = 100 \mu s$; T = 10 ms.
- 8. Measured using an aluminum alloy mirror at d = 1 mm.
- 9. No reflective surface at close proximity.

Typical Performance Curves

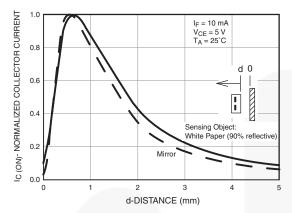


Fig. 1 Normalized Collector Current vs. Distance between device and reflector

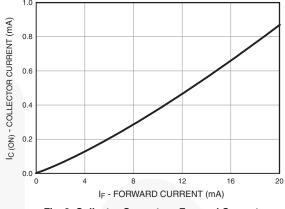


Fig. 2 Collector Current vs. Forward Current

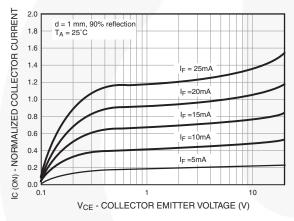


Fig. 3 Normalized Collector Current vs. Collector to Emitter Voltage

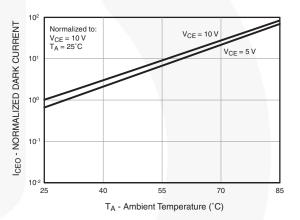


Fig. 4 Collector Emitter Dark Current (Normalized) vs. Ambient Temperature

Typical Performance Curves (Continued)

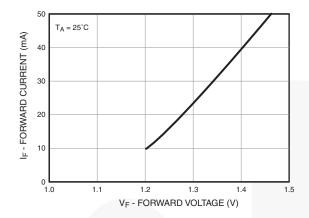


Fig. 6 Forward Current vs. Forward Voltage

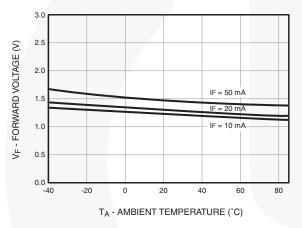


Fig. 8 Forward Voltage vs. Ambient Temperature

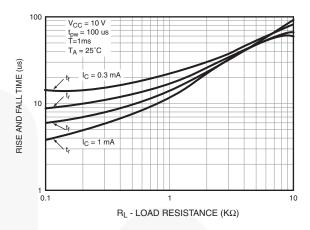


Fig. 7 Rise and Fall Time vs. Load Resistance

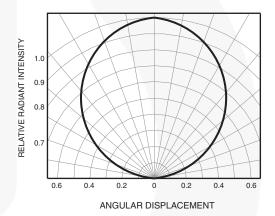
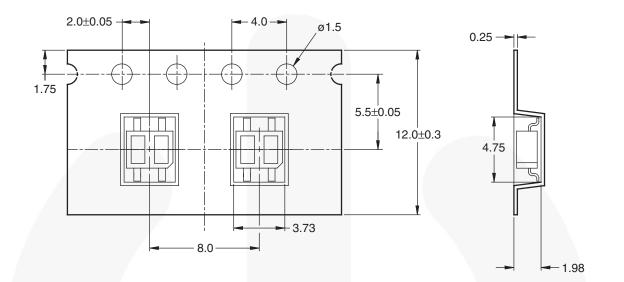


Fig. 8 Radiation Diagram

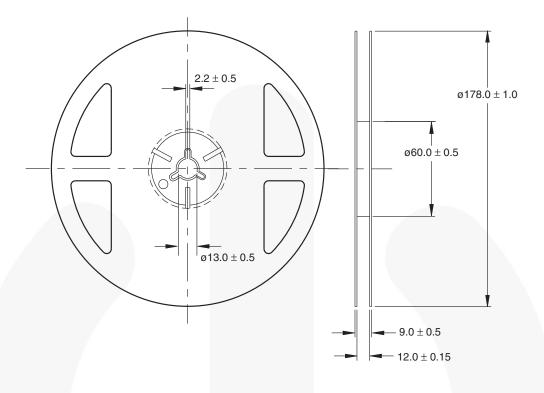
Taping Dimensions for GR option

Progressive Direction

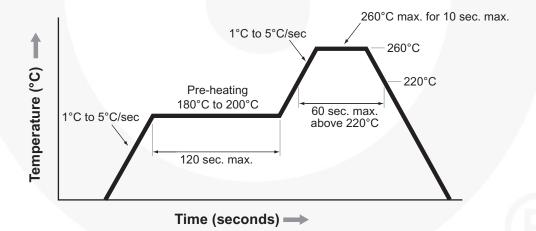


General tolerance ±0.1 Dimensions in mm

Reel Dimensions



Reflow Profile



Note: Reflow soldering should not be done more than twice.





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